

### Description

The DFI600HF17I4RE1 is a Half Bridge IGBT Power Module. It integrates high performance IGBT chips designed for the applications such as High Power supply and Motor control.



### Features

- Blocking voltage:1700V
- Low saturation voltage  $V_{CE(sat)}$
- Low Switching Losses
- 150°C maximum junction temperature
- Thermistor inside

### Applications

- High Power Switching Applications
- Motor Drives
- Solar inverter Systems
- Wind Turbines

### Circuit diagram

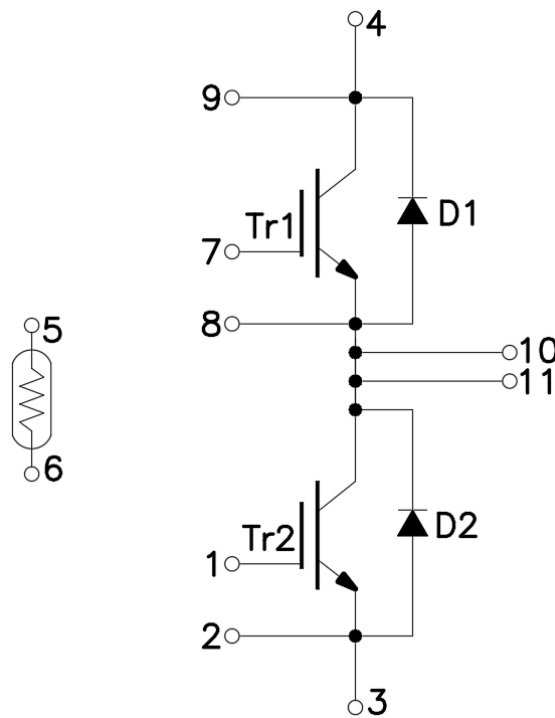


Figure 1. Out drawing & circuit diagram for DFI600HF17I4RE1

### Pin Configuration and Marking Information

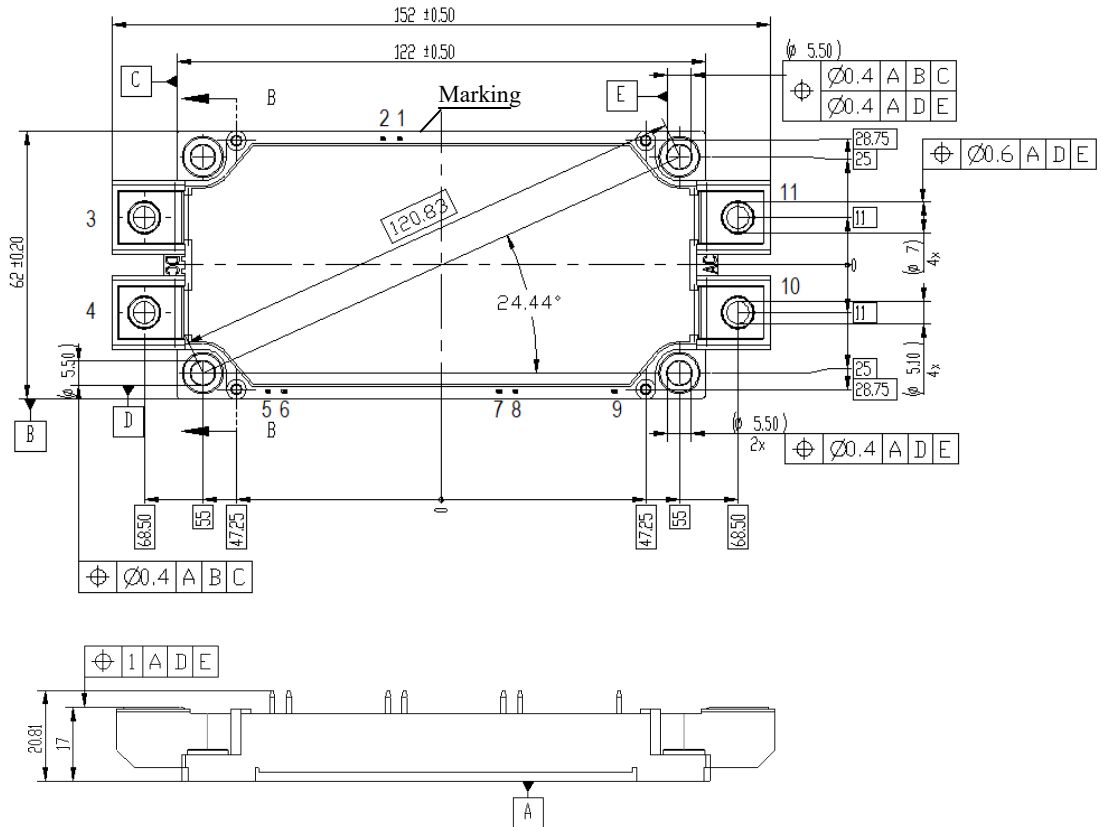


Figure 2. Pin configuration

### Module

Parameter	Conditions	Value	Unit
Isolation Voltage	RMS, $f = 50\text{Hz}$ , $t = 1\text{min}$	3.4	KV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink terminal to terminal	14.5 13	mm
Clearance	terminal to heatsink terminal to terminal	12.5 10	mm
CTI	-	>225	-
Module lead resistance, terminals–chip	$T_c = 25^\circ\text{C}$	0.8	m $\Omega$
Mounting torque for module mounting	M5, M6	3 to 6	Nm
Weight	-	420	g

### Maximum Ratings (T<sub>j</sub>=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V <sub>CES</sub>	Collector-Emitter Voltage	G-E Short	1700	V
V <sub>GES</sub>	Gate-Emitter Voltage	C-E Short	±20V	V
I <sub>C</sub>	DC Continuous Collector Current	T <sub>C</sub> =100°C	650	A
I <sub>CM</sub>	Pulse Collector Current	t <sub>p</sub> =1ms, Note1	1300	A
P <sub>C</sub>	Maximum Power Dissipation	T <sub>C</sub> =25°C, T <sub>j</sub> =150°C(IGBT)	3906	W
I <sub>F</sub>	Diode Forward Current	-	650	A
I <sub>FRM</sub>	Repetitive peak forward Current	t <sub>p</sub> =1ms, Note1	1300	A
I <sup>2</sup> t	I <sup>2</sup> t-value	V <sub>R</sub> =0V, t <sub>p</sub> =10ms, T <sub>j</sub> =125°C (Diode)	36000	A <sup>2</sup> s
T <sub>j</sub>	junction temperature	-	-40 to 150	°C
T <sub>stg</sub>	Storage temperature	-	-40 to 125	°C

Note1: Pulse width limited by maximum junction temperature

### NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
R <sub>25</sub>	Resistance	T <sub>C</sub> =25°C	-	5	-	kΩ
ΔR/R	Deviation of R100	T <sub>C</sub> =100°C, R <sub>100</sub> =493Ω	5	-	5	%
P <sub>25</sub>	Power dissipation	T <sub>C</sub> =25°C	-	-	20	mW
B <sub>25/50</sub>	B-value	R <sub>2</sub> = R <sub>25</sub> exp [B <sub>25/50</sub> (1/T <sub>2</sub> - 1/(298,15 K))]	-	3375	-	K
B <sub>25/80</sub>	B-value	R <sub>2</sub> = R <sub>25</sub> exp [B <sub>25/80</sub> (1/T <sub>2</sub> - 1/(298,15 K))]	-	3411	-	K
B <sub>25/100</sub>	B-value	R <sub>2</sub> = R <sub>25</sub> exp [B <sub>25/100</sub> (1/T <sub>2</sub> - 1/(298,15 K))]	-	3433	-	K

### IGBT Electrical characteristics (T<sub>j</sub>=25°C unless otherwise specified, chip: Target)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V <sub>CE(sat)</sub> (Chip)	Collector-Emitter Saturation Voltage	I <sub>C</sub> =600A V <sub>GE</sub> =15V	T <sub>j</sub> =25°C	-	1.6	1.9	V
			T <sub>j</sub> =125°C	-	1.95	-	V
			T <sub>j</sub> =150°C	-	2.03	-	V
V <sub>GE(th)</sub>	Gate-Emitter threshold Voltage	I <sub>C</sub> =24mA, V <sub>CE</sub> =V <sub>GE</sub>		5.2	5.8	6.5	V
Q <sub>G</sub>	Gate charge	V <sub>GE</sub> = -15V to +15V		-	6.2	-	uC
R <sub>Gint</sub>	Internal gate resistor		T <sub>j</sub> =25°C	-	1.7	-	Ω
C <sub>ies</sub>	Input Capacitance	V <sub>CE</sub> =25V, V <sub>GE</sub> =0V f=1MHz	T <sub>j</sub> =25°C	-	49.5	-	nF
C <sub>res</sub>	Reverse transfer Capacitance			-	0.75	-	nF
I <sub>CES</sub>	Collector- Emitter Cut off Current	V <sub>CE</sub> =1700V, V <sub>GE</sub> =0V	T <sub>j</sub> =25°C	-	-	4.0	mA
I <sub>GES</sub>	Gate-Emitter Leakage Current	V <sub>GE</sub> =20V, V <sub>CE</sub> =0V	T <sub>j</sub> =25°C	-	-	1.8	uA
t <sub>d(on)</sub>	Turn-on delay time	V <sub>CC</sub> =900V I <sub>C</sub> = 600A V <sub>GE</sub> =+15V/-8V R <sub>G</sub> =1.0Ω Inductive load	T <sub>j</sub> =25°C	-	205	-	ns
			T <sub>j</sub> =150°C	-	207	-	
t <sub>r</sub>	Rise time		T <sub>j</sub> =25°C	-	125	-	ns
			T <sub>j</sub> =150°C	-	188	-	
t <sub>d(off)</sub>	Turn-off delay time		T <sub>j</sub> =25°C	-	570	-	ns
			T <sub>j</sub> =150°C	-	735	-	
t <sub>f</sub>	Fall time		T <sub>j</sub> =25°C	-	370	-	ns
			T <sub>j</sub> =150°C	-	680	-	
E <sub>on</sub>	Turn-on power dissipation		T <sub>j</sub> =25°C	-	234	-	mJ
			T <sub>j</sub> =150°C	-	383	-	
E <sub>off</sub>	Turn-off power dissipation	T <sub>j</sub> =25°C	-	134	-	mJ	
		T <sub>j</sub> =150°C	-	205	-		
I <sub>sc</sub>	SC data	V <sub>GE</sub> <15V V <sub>CC</sub> =1000V	T <sub>j</sub> =150°C t <sub>p</sub> <10us	-	3000	-	A
R <sub>th(j-c)</sub>	Thermal Resistance, Junction to Case (IGBT)			-	0.032	-	°C/W
R <sub>th(c-s)</sub>	Thermal Resistance, Case to sink (Conductive Grease applied)			-	0.015	-	°C/W

### Freewheeling Diode Electrical characteristics (T<sub>j</sub>=25°C unless otherwise specified, chip:

Target)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max		
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> =750A V <sub>GE</sub> =0V	T <sub>j</sub> =25°C	-	1.9	2.2	V
			T <sub>j</sub> =150°C	-	1.9	-	
t <sub>rr</sub>	Reverse recovery time	(Switch side) V <sub>CC</sub> =900V, I <sub>c</sub> =600A V <sub>GE</sub> =+15V/-8V	T <sub>j</sub> =25°C	-	1.08	-	us
			T <sub>j</sub> =150°C	-	1.51	-	
I <sub>RM</sub>	Peak reverse recovery Current	R <sub>G</sub> =1.0Ω (FRD side)	T <sub>j</sub> =25°C	-	270	-	A
			T <sub>j</sub> =150°C	-	333	-	
Q <sub>rr</sub>	Recovered charge	V <sub>rr</sub> =900V, I <sub>F</sub> =600A V <sub>GE</sub> =-8V	T <sub>j</sub> =25°C	-	112	-	uC
			T <sub>j</sub> =150°C	-	244	-	
E <sub>rr</sub>	Reverse recovered energy	Inductive load switching operation	T <sub>j</sub> =25°C	-	53	-	mJ
			T <sub>j</sub> =150°C	-	125	-	
R <sub>th(j-c)</sub>	Thermal Resistance, Junction to Case (Diode)		-	0.042	-	°C/W	
R <sub>th(c-s)</sub>	Thermal Resistance, Case to sink (Conductive Grease applied)		-	0.015	-	°C/W	

### Test Conditions

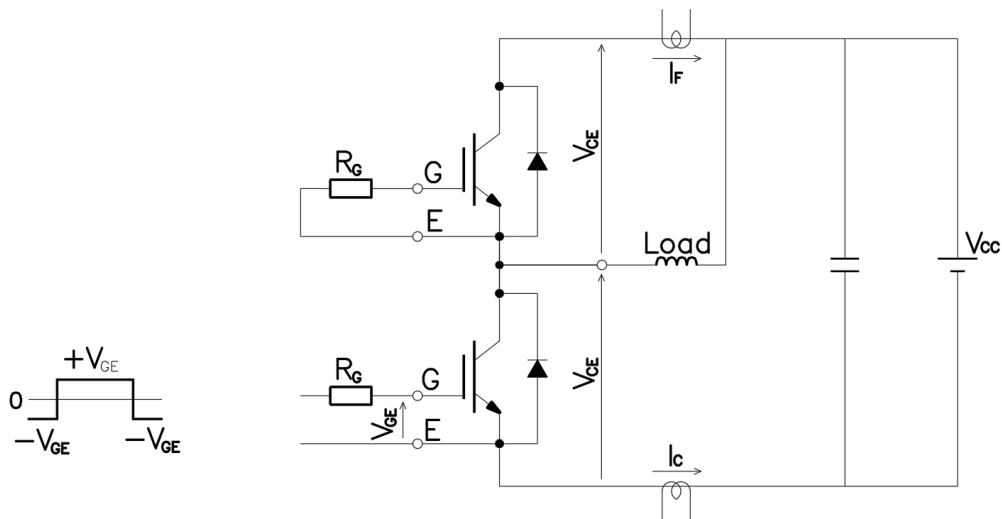


Figure 3. Switching time measure circuit

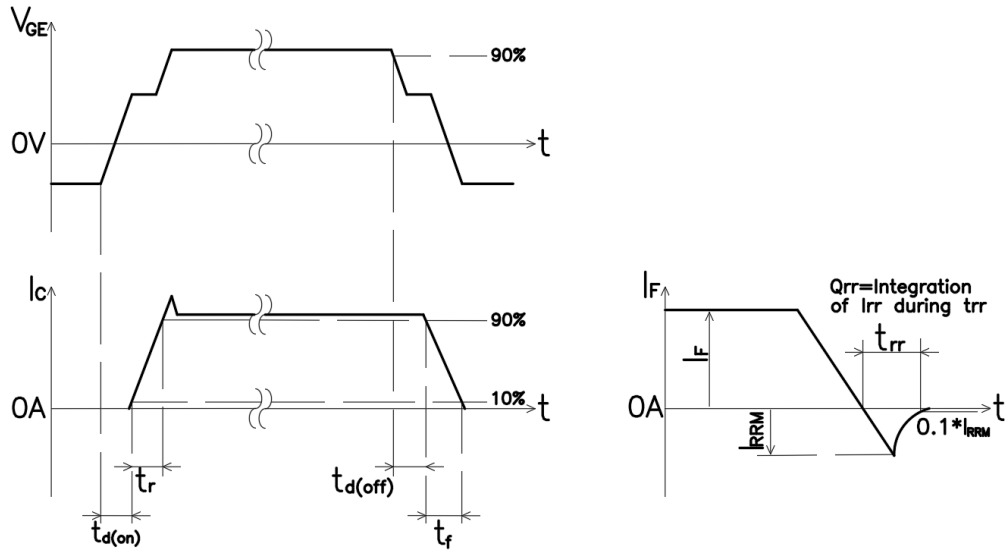


Figure 4. Switching time definition

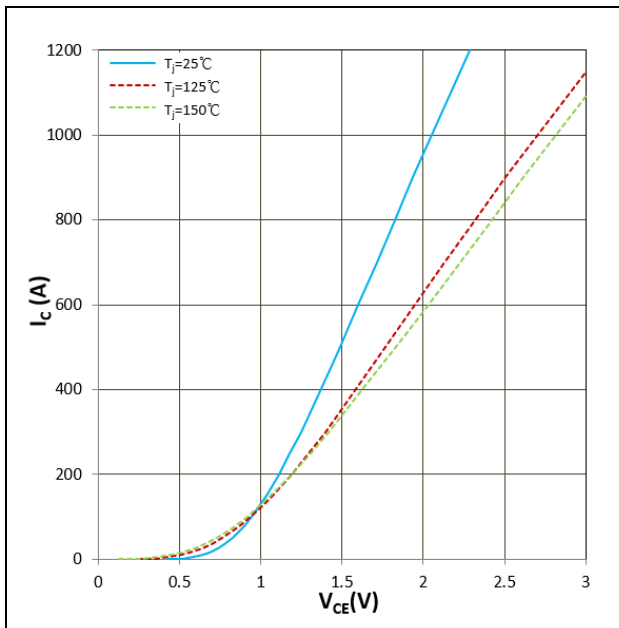


Figure 5.  $I_c$  vs  $V_{CE}$   
 $V_{GE} = 15V$

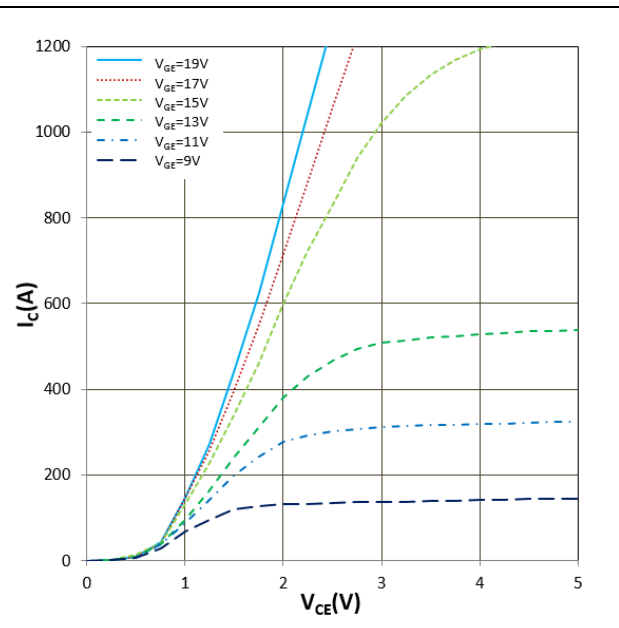


Figure 6.  $I_c$  vs  $V_{CE}$   
 $T_j = 150^\circ C$

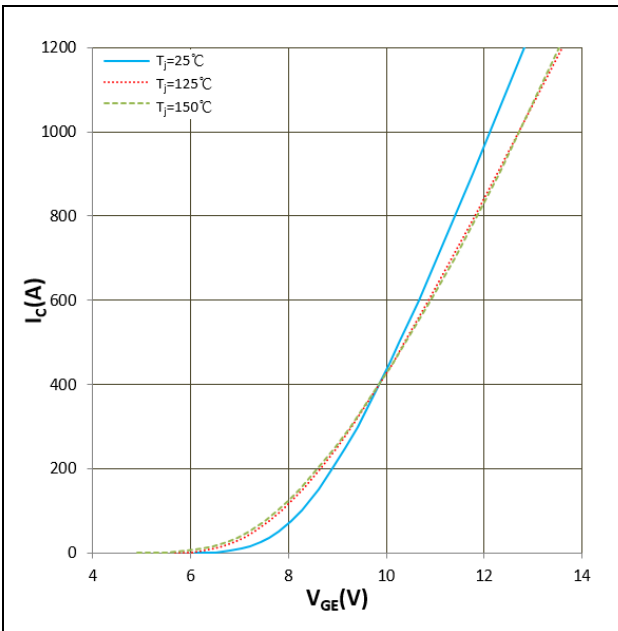


Figure 7.  $I_c$  vs  $V_{GE}$   
 $V_{CE} = 20V$

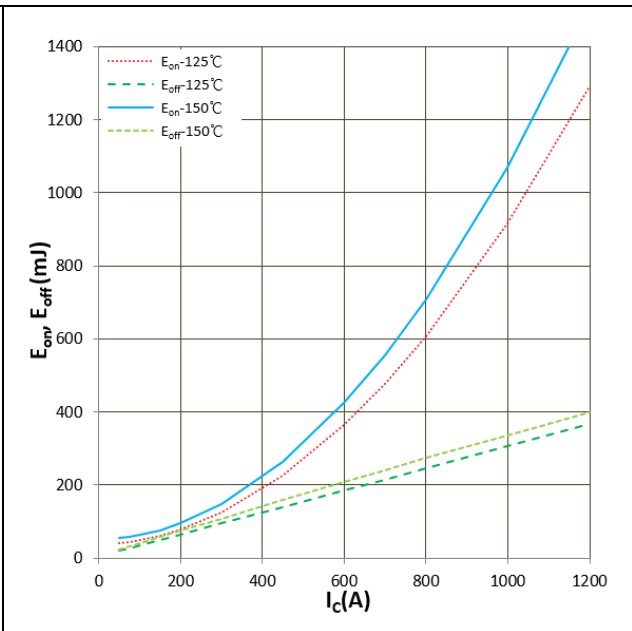


Figure 8.  $E_{on}, E_{off}$  vs  $I_c$ (Typ)  
 $V_{CC} = 900V, V_{GE} = +15V/-8V, R_G = 1.0\Omega$   
Inductive Load

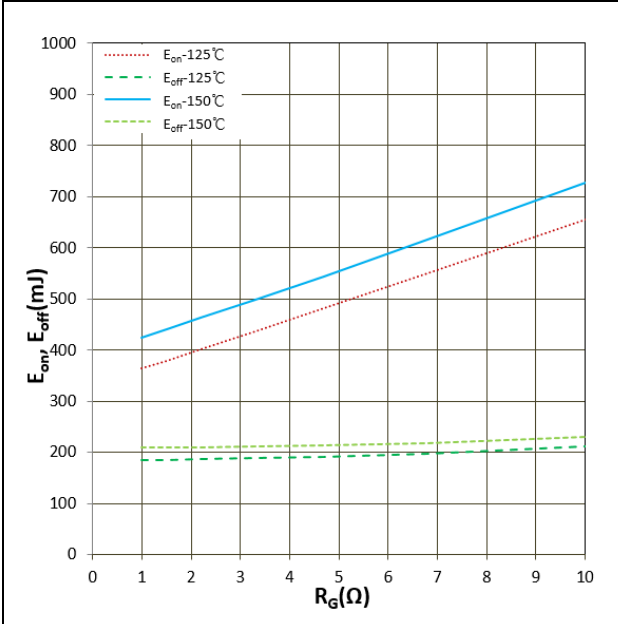


Figure 9.  $E_{on}, E_{off}$  vs  $R_g$ (Typ)  
 $V_{CC} = 900V, V_{GE} = +15V/-8V, I_c = 600A$   
Inductive Load

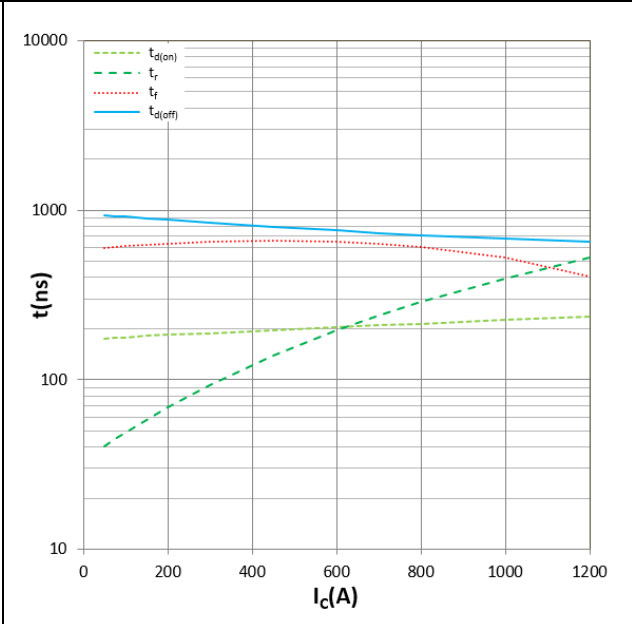


Figure 10. Switching time vs  $I_c$ (Typ)  
 $V_{CC} = 900V, V_{GE} = +15V/-8V, R_G = 1.0\Omega$   
 $T_j = 150^\circ C$ , Inductive Load

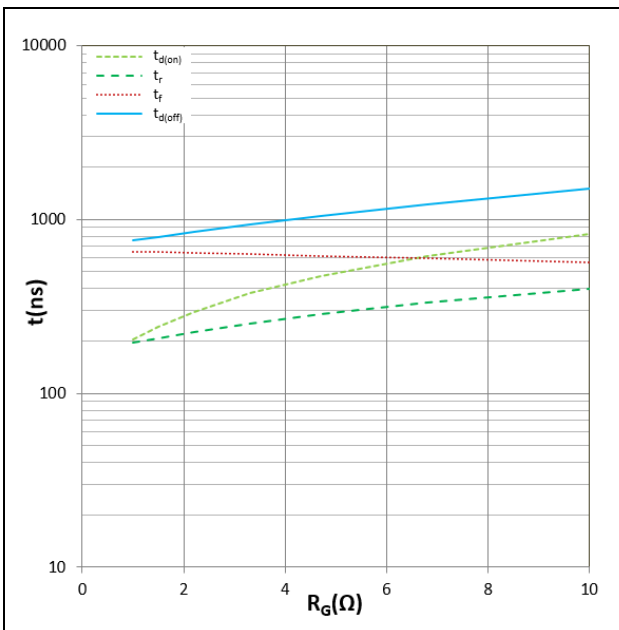


Figure 11. Switching time vs  $R_G$ (Typ)  
 $V_{CC}=900V$ ,  $V_{GE}=+15V/-8V$ ,  $I_C=600A$   
 $T_j=150^\circ C$ , Inductive Load

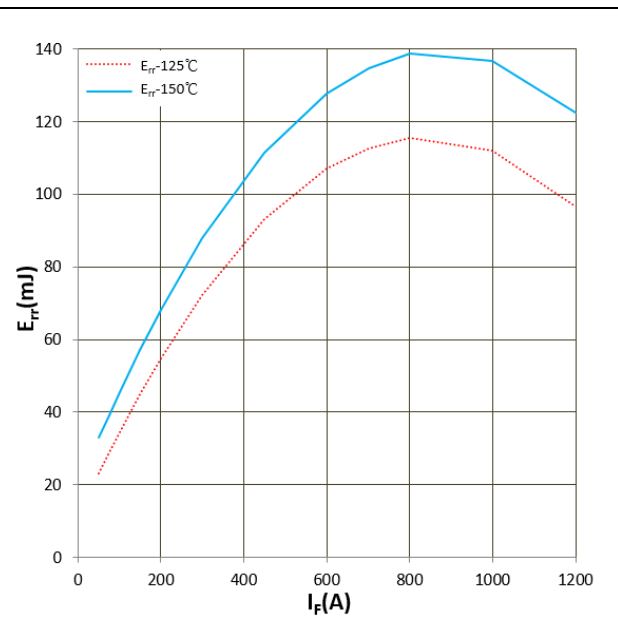


Figure 12.  $E_{rr}$  vs  $I_F$ (Typ)  
 $V_{CC}=900V$ ,  $V_{GE}=+15V/-8V$ ,  $R_G=1.0\Omega$   
 Inductive Load

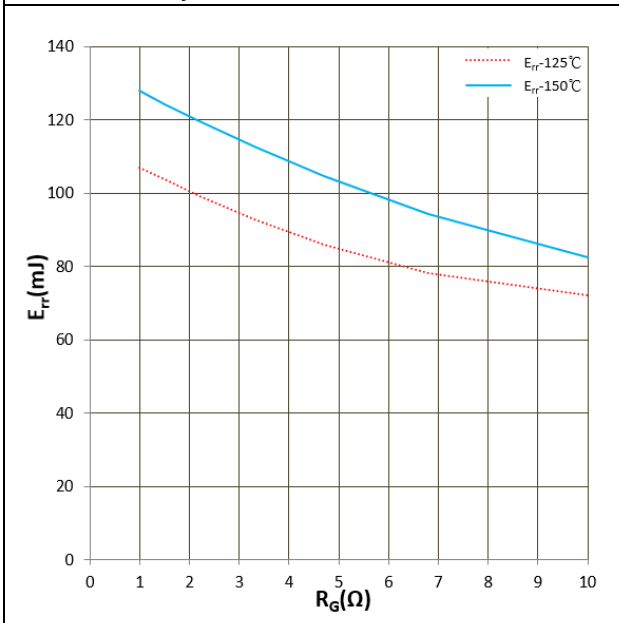


Figure 13.  $E_{rr}$  vs  $R_G$ (Typ)  
 $V_{CC}=900V$ ,  $V_{GE}=+15V/-8V$ ,  $I_F=600A$   
 Inductive Load

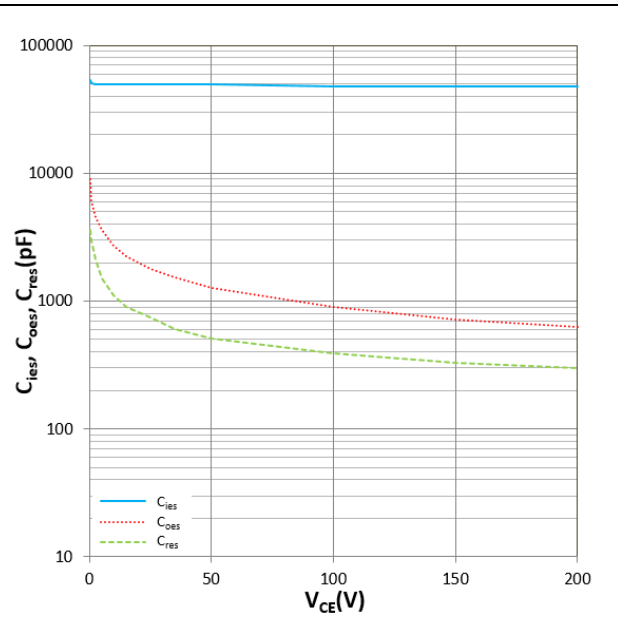


Figure 14.  $C_{ies}$ ,  $C_{oes}$ ,  $C_{res}$  vs  $V_{CE}$   
 $T_j=25^\circ C$ ,  $f=1MHz$



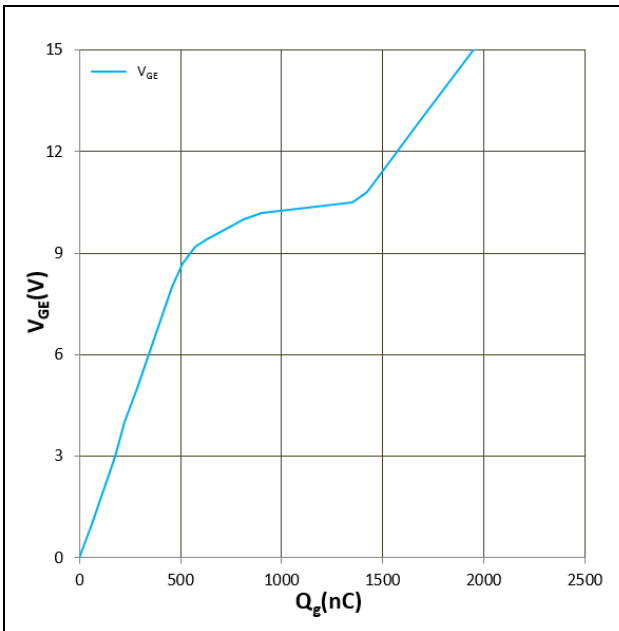


Figure 15. Gate charge

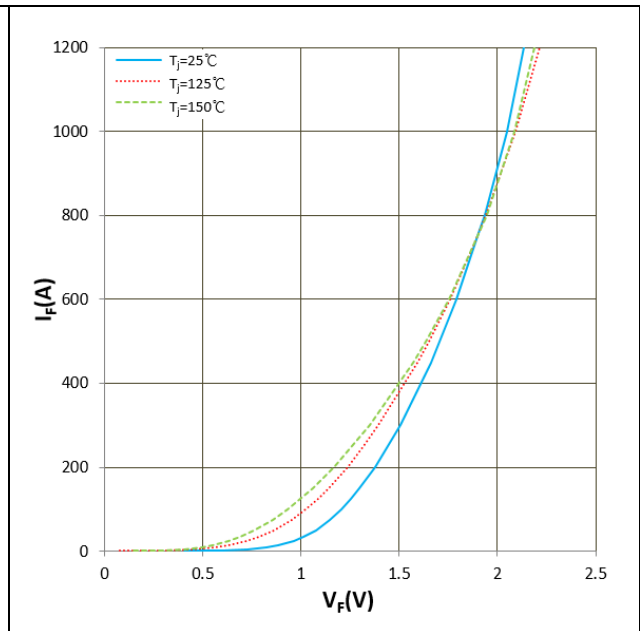


Figure 16. I<sub>F</sub> vs V<sub>F</sub>

### Editing record:

Version	Content	Data
A	First edition	2021.11.15

### IMPORTANT NOTICE

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